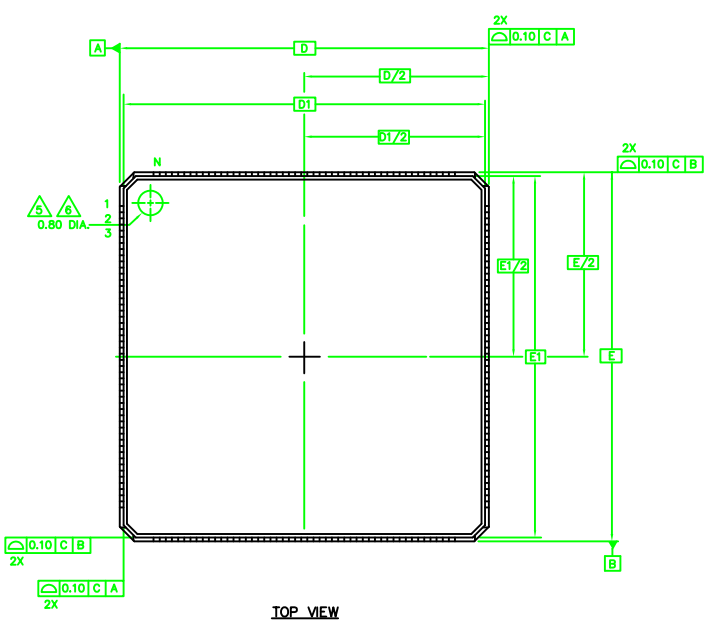
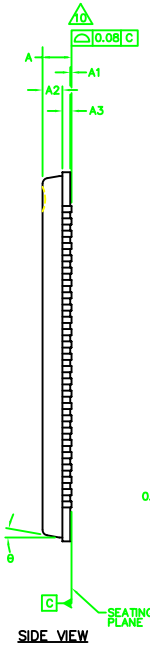
HIGH DENSITY LEADFRAME

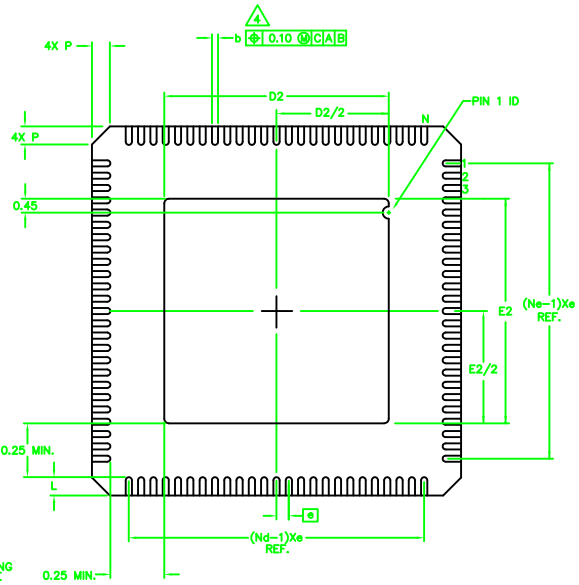
REVISION HISTORY				
REV	DESCRIPTION	DATE	DRAWN BY	RELEASED
00	INITIAL RELEASE PER DCN #A45988.	04/18/2001	BBOLA	SSJ
01	INC. PER DCN #A46877.	06/07/2001	BBOLA	SSJ
02	INC. PER DCN #A51601.	08/03/2001	BBOLA	HIJ
03	INC. PER DCN #A53185.	11/09/2001	HIJ	HIJ



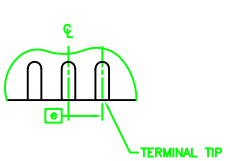
TOP VIEW



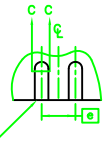
SIDE VIEW



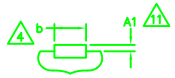
BOTTOM VIEW



FOR ODD TERMINAL/SIDE



FOR EVEN TERMINAL/SIDE



SECTION "C-C"
SCALE: NONE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL X.X ±0.1 mm X.XX ±0.05 mm X.XXX ±0.025 mm
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 1994
MATERIAL SEE CHART ABOVE
FINISH SEE CHART ABOVE
PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS		DATE
DRAWN	HI JEON	09/29/2001
CHECKED	SS JANG	09/29/2001
APPROVED	SS JANG	09/29/2001
RELEASED	SO KANG	11/05/2001

Amkor Technology, Inc. Chandler, Arizona, USA
Anam Semiconductor, Inc., Seoul, Korea
Amkor Technology Philippines, Inc. Manila, Philippines

TITLE: PACKAGE OUTLINE, MLF2, 12 X 12 mm BODY

SIZE	DWG NUMBER	REV
A3	45615	03

SCALE	CUSTOMER CODE	SHEET
NONE	N/A	1 OF 5

FORM NO. MDFORM3J.DWG